

ZLLS500 SURFACE MOUNT SCHOTTKY BARRIER DIODE

Product Summary

- V_R = 40V
- I_F = 0.7A
- I_R = 10μA

Description and Applications

This compact SOT23 packaged Schottky diode offers users an excellent performance combination comprising high current operation, extremely low leakage and low forward voltage ensuring suitability for applications requiring efficient operation at higher temperatures (above 85°C) see Operational efficiency chart on page 3.

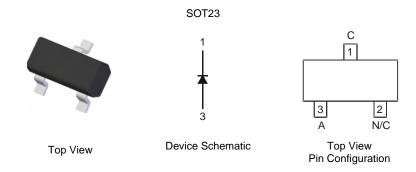
- DC DC Converters
- Strobes
- Mobile Telecomms
- Charging circuits
- Motor Control

Features and Benefits

- Extremely low leakage (10μA @30V)
- High current capability (I_F = 0.7A)
- Low V_F, fast switching Schottky
- ZLLS500 complements low temperature equivalent ZHCS500
- Package thermally rated to 150°C
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Weight: 0.0089 grams (approximate)

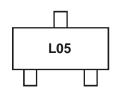


Ordering Information (Note 1)

Device	Packaging	Shipping	
ZLLS500TA	SOT23	3000/Tape & Reel	
ZLLS500TC	SOT23	10000/Tape & Reel	

Notes: 1. For Packaging Details, go to our website at http://www.diodes.com.

Marking Information



L05 = Product Type Marking Code



Maximum Ratings @T_A = 25°C unless otherwise specified

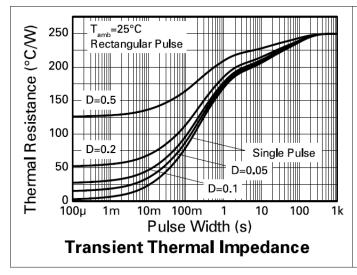
Characteristic		Symbol	Value	Units
Continuous Reverse Voltage		ous Reverse Voltage V _R		V
Continuous Forward Current		I _F	0.7	A
Peak Repetitive Forward Current Rectangular Pulse Duty Cycle		I _{FPK}	1.14	А
Non Repetitive Forward Current	t ≤ 100μs		13	A
	t ≤ 10ms	IFSM	3.2	A

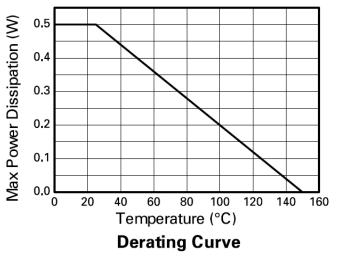
Thermal Characteristics

Characteristic		Symbol	Value	Unit
Power Dissipation, T _A = 25°C Single Die Continuous Single Die Measured at t < 5 secs		P _D	500 630	mW
Thermal Resistance, Junction to Ambient (Note 2) (Note 3)		$R_{\theta JA}$	250 198	
Junction Temperature		TJ	150	°C
Storage Temperature Range		T _{STG}	-55 to +150	°C

Notes:

- 2. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- 3. For a device surface mounted on FR4 PCB measured at t < 5 secs.







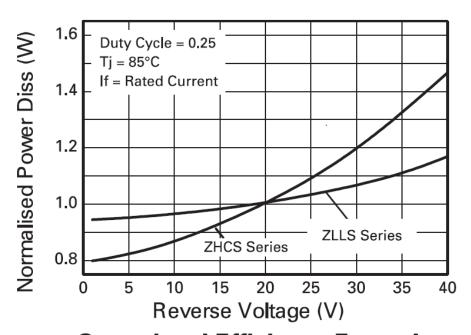
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage	V _{(BR)R}	40	-	-	V	$I_R = 200 \mu A$
		-	305	360		$I_F = 50 \text{mA}$
		-	335	390		I _F = 100mA
		-	395	450		$I_F = 250 \text{mA}$
Famuerd Voltage (Note 4)		-	465	530		$I_F = 500 \text{mA}$
Forward Voltage (Note 4)	V _F	-	550	630	mV	I _F = 750mA
		-	620	710		I _F = 1A
		-	710	800		I _F = 1.5A
		-	415	-		I _F = 500mA, T _A = 100°C
Reverse Current	,	-	6	10	μΑ	V _R = 30V
	I _R	-	370	-		$V_R = 30V, T_A = 85^{\circ}C$
Diode Capacitance	C _D	-	16	-	pF	f = 1MHz, V _R = 30V
Reverse Recovery Time	trr	-	3	-	ns	Switched from $I_F = 500$ mA to $V_R = 5.5$ V Measured @ $I_R = 50$ mA
Reverse Recovery Charge	Qrr	-	210	-	рС	di /d t = 500mA/ ns. $R_{\text{source}} = 6\Omega$; $R_{\text{load}} = 10\Omega$

Notes:

4. Measured under pulsed conditions. Pulse width = 300μS. Duty cycle ≤ 2%.

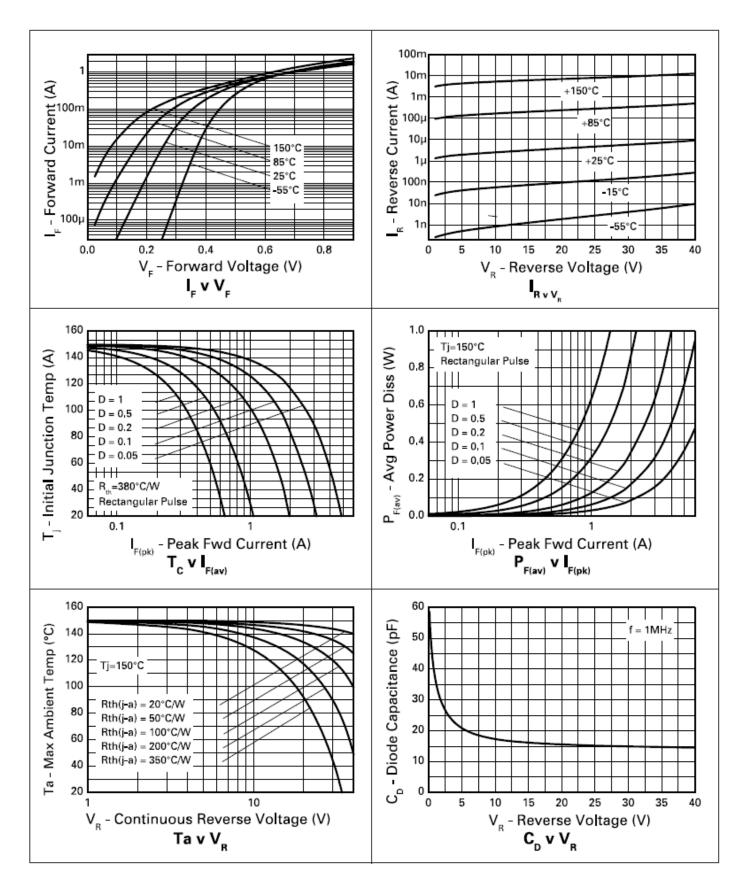
Operational efficiency chart



Operational Efficiency Example

The operational efficiency chart indicates the beneficial use of the ZLLS series diodes in applications requiring higher voltage, higher temperature operation. Circuits requiring low voltage low temperature operation will benefit from using Zetex low V_F ZHCS series diodes.

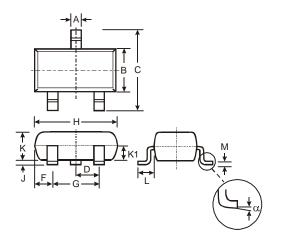




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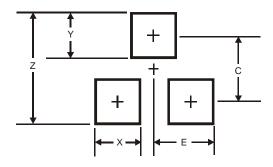


Package Outline Dimensions



SOT23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
С	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Н	2.80	3.00	2.90		
7	0.013	0.10	0.05		
K	0.903	1.10	1.00		
K1	-	-	0.400		
L	0.45	0.61	0.55		
М	0.085	0.18	0.11		
α	0°	8°	-		
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)		
Z	2.9		
Х	0.8		
Y	0.9		
С	2.0		
E	1.35		



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